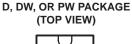
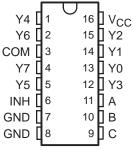
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- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 105°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- 2-V to 5.5-V V<sub>CC</sub> Operation
- Supports Mixed-Mode Voltage Operation on All Ports
- High On-Off Output-Voltage Ratio
- Low Crosstalk Between Switches
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Individual Switch Controls
- Extremely Low Input Current
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)





#### description/ordering information

This 8-channel CMOS analog multiplexer/demultiplexer is designed for 2-V to 5.5-V V<sub>CC</sub> operation.

The SN74LV4051A handles both analog and digital signals. Each channel permits signals with amplitudes up to 5.5 V (peak) to be transmitted in either direction.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

#### ORDERING INFORMATION

TA	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - D	Tape and reel	SN74LV4051ATDREP	LV4051ATEP
-40°C to 105°C	SOIC - DW	Tape and reel	SN74LV4051ATDWREP§	LV4051ATEP
	TSSOP - PW	Tape and reel	SN74LV4051ATPWREP	L4051EP

<sup>‡</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

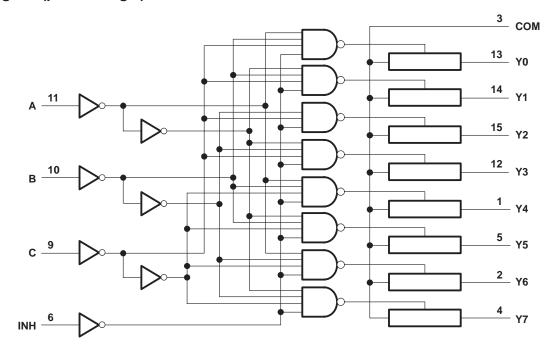


<sup>§</sup> Product Preview.

#### **FUNCTION TABLE**

	INP	UTS		ON
INH	С	В	Α	CHANNEL
L	L	L	L	Y0
L	L	L	Н	Y1
L	L	Н	L	Y2
L	L	Н	Н	Y3
L	Н	L	L	Y4
L	Н	L	Н	Y5
L	Н	Н	L	Y6
L	Н	Н	Н	Y7
Н	Χ	Χ	Χ	None

### logic diagram (positive logic)



### SN74LV4051A-EP 8-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

pply voltage range, V <sub>CC</sub>	
ut voltage range, V <sub>I</sub> (see Note 1)	
itch I/O voltage range, V <sub>IO</sub> (see Notes 1 and 2)	
ut clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–20 mA
diode current, I <sub>IOK</sub> (V <sub>IO</sub> < 0)	–50 mA
itch through current, I <sub>T</sub> (V <sub>IO</sub> = 0 to V <sub>CC</sub> )	±25 mA
ntinuous current through V <sub>CC</sub> or GND	±50 mA
ckage thermal impedance, θ <sub>JA</sub> (see Note 3): D package	73°C/W
DW package	57°C/W
PW package	108°C/W
orage temperature range, T <sub>stg</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT		
Vcc	Supply voltage		2‡	5.5	V		
		V <sub>CC</sub> = 2 V	1.5				
.,	High-level input voltage,	V <sub>CC</sub> = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		.,		
$V_{\text{IH}}$	control inputs	V <sub>CC</sub> = 3 V to 3.6 V	$V_{CC} \times 0.7$		V		
		V <sub>CC</sub> = 4.5 V to 5.5 V	$V_{CC} \times 0.7$				
		V <sub>CC</sub> = 2 V		0.5			
.,	Low-level input voltage,	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V		
$V_{IL}$	control inputs	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V		
		V <sub>CC</sub> = 4.5 V to 5.5 V		$V_{CC} \times 0.3$			
٧ <sub>I</sub>	Control input voltage		0	5.5	V		
V <sub>IO</sub>	Input/output voltage		0	VCC	V		
		V <sub>CC</sub> = 2.3 V to 2.7 V		200			
Δt/Δν	Input transition rise or fall rate	V <sub>CC</sub> = 3 V to 3.6 V		100	ns/V		
		V <sub>CC</sub> = 4.5 V to 5.5 V		20			
TA	Operating free-air temperature		-40	105	°C		
٠,٨	- F - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1						

<sup>‡</sup> With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN74LV4051A-EP 8-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			.,	T,	\ = 25°C	;			
	PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
			2.3 V		38	180		225	
ron	On-state switch resistance	$I_T = 2 \text{ mA}, V_I = V_{CC} \text{ or GND},$ $V_{INH} = V_{II}, \text{ (see Figure 1)}$	3 V		30	150		190	Ω
		THAM TE, (SEE 1.98.18.1)	4.5 V		22	75		100	
		1 0 A V V V (- CND	2.3 V		113	500		600	
ron(p)	Peak on-state resistance	$I_T = 2 \text{ mA}, V_I = V_{CC} \text{ to GND},$ $V_{INH} = V_{II}$	3 V		54	180		225	Ω
,		VIIVIT — VIL	4.5 V		31	100		125	
	Difference in on-state		2.3 V		2.1	30		40	
$\Delta r_{on}$	resistance between	$I_T = 2 \text{ mA}, V_I = V_{CC} \text{ to GND},$ $V_{INH} = V_{II}$	3 V		1.4	20		30	Ω
	switches	·IIVII ·IL	4.5 V		1.3	15		20	
IĮ	Control input current	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±0.1		±1	μΑ
IS(off)	Off-state switch leakage current	$V_I = V_{CC}$ and $V_O = GND$ , or $V_I = GND$ and $V_O = V_{CC}$ , $V_{INH} = V_{IH}$ , (see Figure 2)	5.5 V			±0.1		±1	μΑ
I <sub>S(on)</sub>	On-state switch leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND, V <sub>INH</sub> = V <sub>IL</sub> (see Figure 3)	5.5 V			±0.1		±1	μΑ
Icc	Supply current	$V_I = V_{CC}$ or GND	5.5 V					20	μΑ
C <sub>IC</sub>	Control input capacitance	f = 10 MHz	3.3 V		2				pF
C <sub>IS</sub>	Common terminal capacitance		3.3 V	_	23.4				pF
COS	Switch terminal capacitance		3.3 V		5.7				pF
C <sub>F</sub>	Feedthrough capacitance		3.3 V		0.5				pF

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V $\pm$ 0.2 V (unless otherwise noted)

D4.D	**************************************	FROM	то	TEST	T,	չ = 25°C	;		MAY	LINUT
PAR	AMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C <sub>L</sub> = 15 pF, (see Figure 4)		1.9	10		16	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Yn	C <sub>L</sub> = 15 pF, (see Figure 5)		6.6	18		23	ns
<sup>t</sup> PHZ <sup>t</sup> PLZ	Disable delay time	INH	COM or Yn	C <sub>L</sub> = 15 pF, (see Figure 5)		7.4	18		23	ns
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C <sub>L</sub> = 50 pF, (see Figure 5)		3.8	12		18	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Yn	C <sub>L</sub> = 50 pF, (see Figure 5)		7.8	28	·	35	ns
<sup>t</sup> PHZ <sup>t</sup> PLZ	Disable delay time	INH	COM or Yn	C <sub>L</sub> = 50 pF, (see Figure 5)		11.5	28		35	ns



# SN74LV4051A-EP 8-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted)

DAD	AMETER	FROM	то	TEST	T	λ = 25°C	;	84181	88 A V	
PAR	AMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation delay time	COM or Yn	Yn or COM	C <sub>L</sub> = 15 pF, (see Figure 4)		1.2	6		10	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Yn	C <sub>L</sub> = 15 pF, (see Figure 5)		4.7	12		15	ns
tPHZ tPLZ	Disable delay time	INH	COM or Yn	C <sub>L</sub> = 15 pF, (see Figure 5)		5.7	12		15	ns
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C <sub>L</sub> = 50 pF, (see Figure 4)		2.5	9		12	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Yn	C <sub>L</sub> = 50 pF, (see Figure 5)		5.5	20		25	ns
tPHZ tPLZ	Disable delay time	INH	COM or Yn	C <sub>L</sub> = 50 pF, (see Figure 5)		8.8	20		25	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted)

DAD	AMETER	FROM	то	TEST	TA	√ = 25°C	;	BAIN!	MAN	
PAR	AMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation delay time	COM or Yn	Yn or COM	C <sub>L</sub> = 15 pF, (see Figure 4)		0.6	4		7	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Yn	C <sub>L</sub> = 15 pF, (see Figure 5)		3.5	8		10	ns
<sup>t</sup> PHZ <sup>t</sup> PLZ	Disable delay time	INH	COM or Yn	C <sub>L</sub> = 15 pF, (see Figure 5)		4.4	8		10	ns
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C <sub>L</sub> = 50 pF, (see Figure 4)		1.5	6		8	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Yn	C <sub>L</sub> = 50 pF, (see Figure 5)		4	14		18	ns
tPHZ tPLZ	Disable delay time	INH	COM or Yn	C <sub>L</sub> = 50 pF, (see Figure 5)		6.2	14		18	ns

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# analog switch characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	FROM	то	7707.00	IDITIONS.	.,	T,	ղ = 25°C	;	LINUT
PARAMETER	(INPUT)	(OUTPUT)	TEST CO	NDITIONS	VCC	MIN	TYP	MAX	UNIT
			$C_L = 50 \text{ pF},$		2.3 V		20		
Frequency response (switch on)	COM or Yn	Yn or COM	$R_L = 600 \Omega$ , $f_{in} = 1 MHz$ (sir	ne wave)	3 V		25		MHz
(cimen city			(see Note 5 and		4.5 V		35		
Crosstalk			C <sub>L</sub> = 50 pF,		2.3 V		20		
1 1	COM or Yn	or Yn $R_L = 600 \Omega$ , $f_{in} = 1 \text{ MHz (square wave)}$		3 V		35		mV	
			(see Figure 7)		4.5 V		60		
		Yn or COM	C <sub>L</sub> = 50 pF,		2.3 V		-45		dB
Feedthrough attenuation (switch off)	COM or Yn		$R_L = 600 \Omega$ , $f_{in} = 1 MHz$	3 V		-45			
(Giricin Gir)			(see Note 6 and	d Figure 8)	4.5 V		-45		
			C <sub>L</sub> = 50 pF,	V <sub>I</sub> = 2 V <sub>p-p</sub>	2.3 V		0.1		
Sine-wave distortion	COM or Yn	Yn or COM	$R_L = 10 \text{ k}\Omega,$ $f_{\text{in}} = 1 \text{ kHz}$	V <sub>I</sub> = 2.5 V <sub>p-p</sub>	3 V		0.1		%
			(sine wave) (see Figure 9)	V <sub>I</sub> = 4 V <sub>p-p</sub>	4.5 V		0.1		

NOTES: 5. Adjust  $f_{in}$  voltage to obtain 0-dBm output. Increase  $f_{in}$  frequency until dB meter reads -3 dB.

# operating characteristics, $V_{CC} = 3.3 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER		TEST CONDITIONS		
C <sub>pd</sub>	Power dissipation capacitance	C <sub>L</sub> = 50 pF,	f = 10 MHz	5.9	pF

#### PARAMETER MEASUREMENT INFORMATION

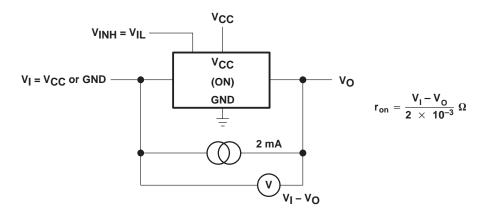
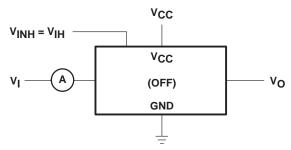


Figure 1. On-State Resistance Test Circuit

<sup>6.</sup> Adjust fin voltage to obtain 0-dBm input.

#### PARAMETER MEASUREMENT INFORMATION



Condition 1:  $V_I = 0$ ,  $V_O = V_{CC}$ Condition 2:  $V_I = V_{CC}$ ,  $V_O = 0$ 

Figure 2. Off-State Switch Leakage-Current Test Circuit

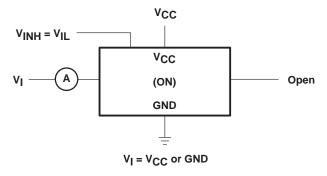


Figure 3. On-State Switch Leakage-Current Test Circuit

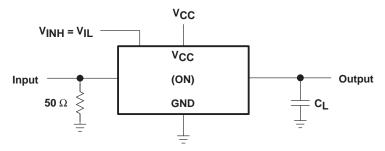


Figure 4. Propagation Delay Time, Signal Input to Signal Output

#### PARAMETER MEASUREMENT INFORMATION

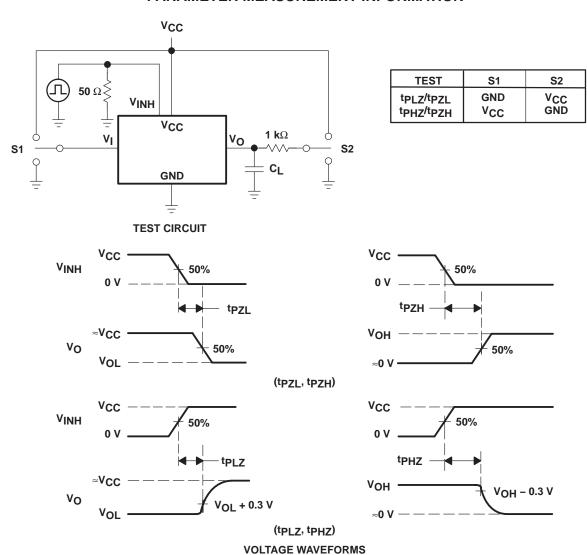


Figure 5. Switching Time (t<sub>PZL</sub>, t<sub>PLZ</sub>, t<sub>PZH</sub>, t<sub>PHZ</sub>), Control to Signal Output

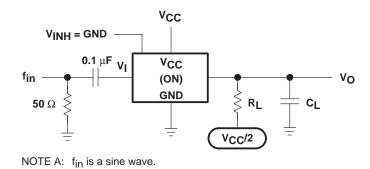


Figure 6. Frequency Response (Switch On)



#### PARAMETER MEASUREMENT INFORMATION

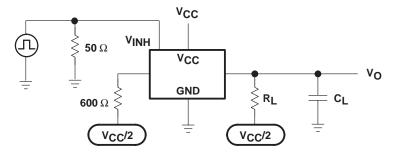


Figure 7. Crosstalk (Control Input, Switch Output)

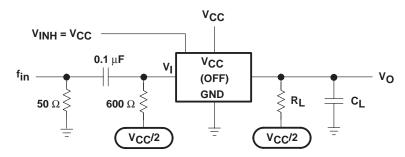


Figure 8. Feedthrough Attenuation (Switch Off)

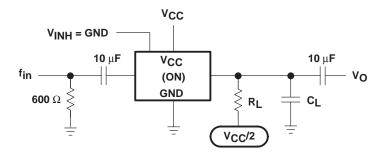


Figure 9. Sine-Wave Distortion

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74LV4051ATDREP	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV4051ATEP
SN74LV4051ATDREP.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV4051ATEP
SN74LV4051ATPWREP	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4051EP
SN74LV4051ATPWREP.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4051EP
V62/03664-01XE	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	L4051EP
V62/03664-01YE	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV4051ATEP

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF SN74LV4051A-EP:

Catalog : SN74LV4051A

• Automotive : SN74LV4051A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

# **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV4051ATDREP	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV4051ATPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV4051ATDREP	SOIC	D	16	2500	353.0	353.0	32.0
SN74LV4051ATPWREP	TSSOP	PW	16	2000	353.0	353.0	32.0

# D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.





SMALL OUTLINE PACKAGE



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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